

ABSTRACT OF THE DISCLOSURE

A principal object is to provide a semiconductor device that uses a semiconductor sealing epoxy resin composition being excellent in visibility of a laser mark and in fluidity characteristics. A semiconductor chip is sealed with a package formed of an epoxy resin. A laser mark is printed on a surface of the package. The color difference between the color of the laser mark and the color of the surface of the package where the laser mark is not formed, as measured by means of a colorimeter, shows a value of 10 or more.

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